

WHAT IS CLAIMED IS:

1. A semiconductor laser device comprising:

a semiconductor laser element;

5 a generally circular stem to which said semiconductor laser element is mounted, said stem having at least one notch at an outer peripheral part thereof; and

a cap covering said semiconductor laser element, said cap having a flange for welding to an upper surface of the stem, wherein

10 said flange of the cap is provided with at least one cut-off portion; and

when said cap is in a state welded to the stem, said or each cut-off portion of the flange is positioned in a region of the stem in which no notch is present.

15

2. The semiconductor laser device according to claim 1, wherein the number of notches provided at the outer peripheral part of the stem and the number of cut-off portions of the flange are three or more.

20

3. The semiconductor laser device according to claim 1, wherein a difference between a radius of the circular stem and that of the flange is 0.4 mm or less.

4. The semiconductor laser device according to claim 1, wherein a venthole is provided in a side surface of the cap at a location corresponding to said cut-off portion.

5 5. A method for producing the semiconductor laser device of claim 1, wherein when welding a flange of a cap, which is provided with at least one cut-off portion, to an upper surface of a generally circular stem having at least one notch at an outer peripheral part thereof, the method
10 comprises:

positioning the stem using said at least one notch of the stem; and

positioning the cap using said at least one cut-off portion of the flange of the cap such that said or each
15 cut-off portion is located in a region having no notch of the stem.

6. The method according to claim 5, wherein said flange has a plurality of cut-off portions, and partial
20 flange portions into which the flange is divided by these cut-off portions are welded to the stem by independent electrodes and power supplies.